Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π–MOSIII)

2SK2700

Chopper Regulator, DC–DC Converter and Motor Drive Applications

 $\begin{array}{ll} \bullet & Low\ drain-source\ ON\ resistance & : R_{DS}\ (ON) = 3.7\ \Omega\ (typ.) \\ \bullet & High\ forward\ transfer\ admittance & : |Y_{fs}| = 2.6\ S\ (typ.) \\ \bullet & Low\ leakage\ current & : I_{DSS} = 100\ \mu A\ (max)\ (V_{DS} = 720\ V) \\ \bullet & Enhancement\ mode & : V_{th} = 2.0 {\sim} 4.0\ V\ (V_{DS} = 10\ V,\ I_{D} = 1\ mA) \\ \end{array}$

Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	900	V	
Drain–gate voltage (R _{GS} = 20 kΩ)		V_{DGR}	900	V	
Gate-source voltage		V_{GSS}	±30	٧	
Drain current	DC (Note 1)	I _D	3	Α	
	Pulse (Note 1)	I_{DP}	9	Α	
Drain power dissipation	n (Tc = 25°C)	P _D	40	W	
Single pulse avalanche energy (Note 2)		E _{AS}	295	mJ	
Avalanche current		I _{AR}	3	Α	
Repetitive avalanche e	nergy (Note 3)	E _{AR}	4	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature ra	ange	T _{stg}	-55~150	°C	

Weight: 1.9 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	3.125	°C / W
Thermal resistance, channel to ambient	R _{th (ch-a)}	62.5	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 60.0 mH, R_{G} = 25 Ω , I_{AR} = 3 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.

Please handle with caution.



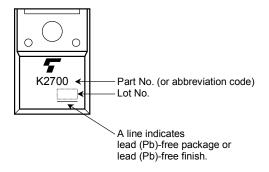
Electrical Characteristics (Ta = 25°C)

Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±30 V, V _{DS} = 0 V		_	±10	μΑ
Gate-source bre	eakdown voltage	V (BR) GSS	I _G = ±10 μA, V _{DS} = 0 V	±30	_	_	V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 720 V, V _{GS} = 0 V	_	_	100	μΑ
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	900	_	_	V
Gate threshold v	/oltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 1.5 A	_	3.7	4.3	Ω
Forward transfer	r admittance	Y _{fs}	V _{DS} = 20 V, I _D = 1.5 A	0.65	2.6	_	S
Input capacitano	e	C _{iss}			750	_	pF
Reverse transfer capacitance		C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	_	10	_	
Output capacitance		C _{oss}]		70	_	
Switching time	Rise time	t _r	$V_{GS} \stackrel{10V}{_{0V}} \stackrel{I_{D}=1.5A}{_{\sim}} \circ V_{out}$ $V_{GS} \stackrel{10V}{_{0V}} \stackrel{I_{D}=1.5A}{_{\sim}} \circ V_{out}$ $V_{DD} \stackrel{1}{=} 200V$ $V_{DD} \stackrel{1}{=} 200V$ $Duty \leq 1\%, \ t_{W} = 10 \mu s$	_	15	_	
	Turn-on time	t _{on}		_	55	_	ns
	Fall time	t _f		_	30	_	
	Turn-off time	t _{off}		_	110	_	
Total gate charge (gate–source plus gate–drain)		Qg		_	25	_	
Gate-source charge		Q _{gs}	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3 \text{ A}$		13	_	nC
Gate-drain ("miller") Charge		Q_{gd}			12	_	

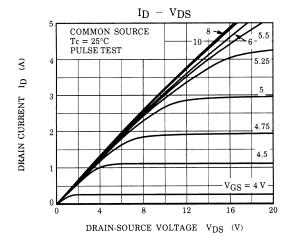
Source-Drain Ratings and Characteristics (Ta = 25°C)

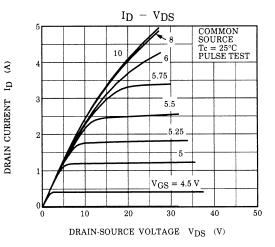
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	-	3	Α
Pulse drain reverse current (Note 1)	I _{DRP}	-	_	_	9	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 3 A, V _{GS} = 0 V	_	_	-1.9	V
Reverse recovery time	t _{rr}	I _{DR} = 3 A, V _{GS} = 0 V		1100	_	ns
Reverse recovery charge	Q _{rr}	dl _{DR} / dt = 100 A / μs	_	7.2	_	μC

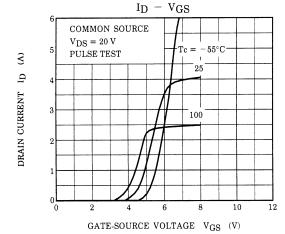
Marking

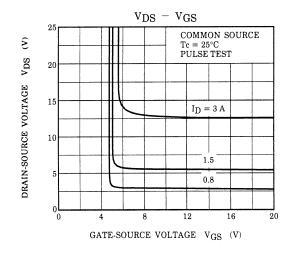


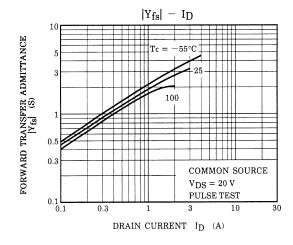
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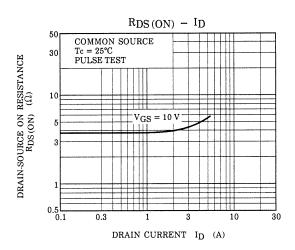


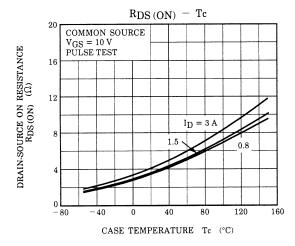


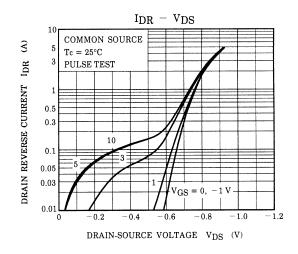


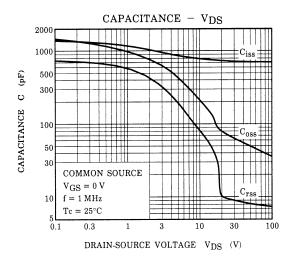


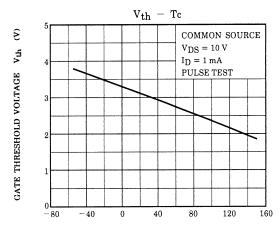


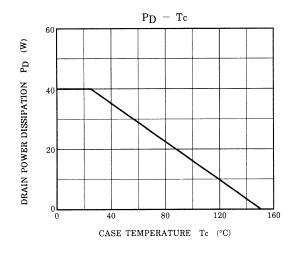


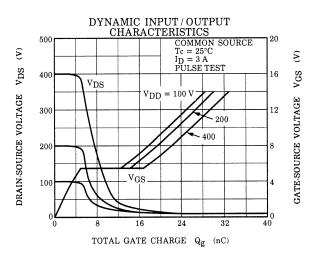


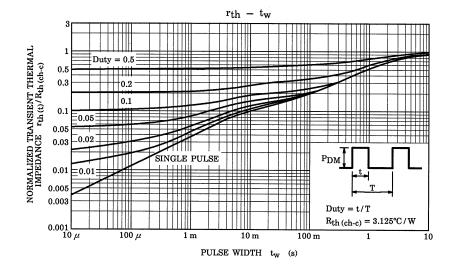


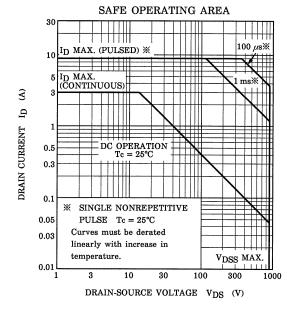


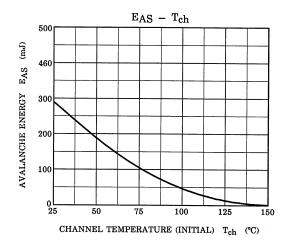


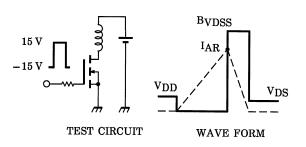












$$R_G = 25 \Omega$$

 $V_{DD} = 90 \text{ V}, L = 60 \text{ mH}$

$$EAS = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

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Handbook" etc..

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